

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT8093408

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
STANLEY KIN SUI CHENG	07/15/2014
EDWARD S. SHERMAN	07/15/2014
HIN HANG HOMER CHEUNG	07/22/2014
KAM YUEN LI	07/22/2014
CHUN WING WONG	07/22/2014
RECEIVING PARTY DATA	
Name:	MEYER INTELLECTUAL PROPERTIES LIMITED
Street Address:	382 KWUN TONG ROAD
City:	KOWLOON
State/Country:	HONG KONG
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17088388
CORRESPONDENCE DATA	
Fax Number:	(561)659-6313
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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ATTORNEY DOCKET NUMBER:	11094-179-1
NAME OF SUBMITTER:	MARK D. PASSLER
SIGNATURE:	/Mark D. Passler/
DATE SIGNED:	08/02/2023
	This document serves as an Oath/Declaration (37 CFR 1.63).
Total Attachments: 4	

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ASSIGNMENT

WHEREAS, We, Stanley Kin Sui Cheng, Edward S. Sherman, Hin Hang Homer Cheung, Kam Yuen Li and Chun Wing Wong, have invented certain new and useful improvements disclosed in an application for United States Letters Patent titled "**Low-Pressure Cooking Method and Cookware Vessel Adapted for the Same**", having application Serial No. 14/285,126 and filed on May 22, 2014.

AND WHEREAS Meyer Intellectual Properties Limited, a British Virgin Islands corporation (hereafter, together with any successors, legal representatives of assign thereof, called "Assignee"), wants to acquire the entire right, title and interest in and to said improvement and application.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I have sold, assigned, transferred and set over, and do hereby sell, assign, transfer and set over to Assignee the entire right, title and interest in and to said improvements, and said application and all non-provisional application claiming priority thereto, as well as divisions, substitutions, continuations and continuations-in-part thereof, and all United States Letters Patents which may be granted thereon and all reissues and extensions thereof, and all priority rights under the International Convention for the Protection of Industrial Property for every member country, and all applications for patents (including related rights such as utility-model registrations, inventor's certificates, and the like) heretofore or hereafter filed for said improvements in any foreign countries, and all patents (including all extensions, renewals and reissues thereof) granted for said improvements in any foreign countries; and we hereby authorize and request the United States Commissioner of Patents and Trademarks, and any officials of foreign countries whose duty it is to issue patents on applications as aforesaid, to issue all patents for said improvements to Assignee in accordance with the terms of this assignment;

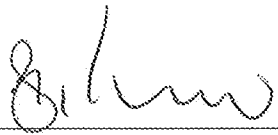
AND I HEREBY covenant that I have the full right to convey the entire rights herein assigned, and that I have not executed, and will not execute any agreement in conflict herewith;

AND I HEREBY further covenant and agree that I will communicate to Assignee any

lawful papers, execute all non-provisional, divisional, continuation, continuations-in-part, substitute and reissue applications, make all rightful oaths and generally do everything possible to aid Assignee to obtain and enforce proper patent protection for said improvements in all countries.

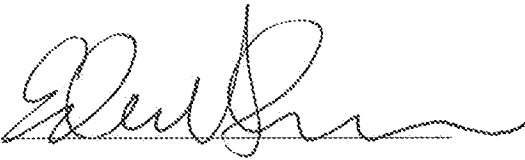
The above-identified application was made or authorized to be made by me. I believe that I am the original inventor or an original joint inventor of a claimed invention in the application. I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

IN TESTIMONY WHEREOF, I hereunto set my hand this:

X 

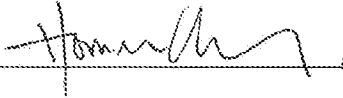
By Stanley Kin Sui Cheng

This 15th day of July, 2014

X 

By Edward S. Sherman

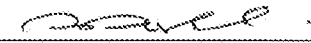
This 15th day of July, 2014

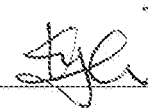
X 

By Hin Hang Homer Cheung

This 22nd day of July, 2014

I, LEE KAM LUN (name of witness) on this 22nd day of
JULY, 2014, at 382 KWUN TONG RD, HONG KONG (location) personally
witnessed the signature of Hin Hang Homer Cheung.

X  (signature of witness)

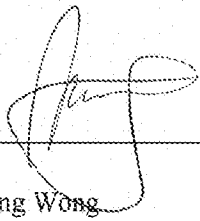
X 

By Kam Yuen Li

This 22nd day of July, 2014

I, LEE KAM LUN (name of witness) on this 22nd day of
JULY, 2014, at 382 KWUN TONG RD, HONG KONG (location) personally
witnessed the signature of Kam Yuen Li.

X  (signature of witness)

X 
By Chun Wing Wong

This 22nd day of July, 2014

I, Lai Yin Law (name of witness) on this 22nd day of
July, 2014, at Hong Kong (location) personally
witnessed the signature of Chun Wing Wong.

x  (signature of witness)